

## Notice

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### 7. Washing

1. Please evaluate the capacitor using actual cleaning equipment and conditions to confirm the quality, and select the solvent for cleaning.

2. Unsuitable cleaning may leave residual flux or other foreign substances, causing deterioration of electrical characteristics and the reliability of the capacitors.

### 8. Coating

1. A crack may be caused in the capacitor due to the stress of the thermal contraction of the resin during curing process.  
The stress is affected by the amount of resin and curing contraction.  
Select a resin with low curing contraction.  
The difference in the thermal expansion coefficient between a coating resin or a molding resin and the capacitor may cause the destruction and deterioration of the capacitor such as a crack or peeling, and lead to the deterioration of insulation resistance or dielectric breakdown.  
Select a resin for which the thermal expansion coefficient is as close to that of the capacitor as possible.  
A silicone resin can be used as an under-coating to buffer against the stress.

2. Select a resin that is less hygroscopic.  
Using hygroscopic resins under high humidity conditions may cause the deterioration of the insulation resistance of a capacitor.  
An epoxy resin can be used as a less hygroscopic resin.
3. The halogen system substance and organic acid are included in coating material, and a chip corrodes by the kind of Coating material.  
Do not use strong acid type.

#### <Applicable to ZRB Series>

4. Loss suppress acoustic noise may be caused in ZRB series due to the resin during curing process. Please contact our sales representative or product engineers on the apply to resin during curing process.

### Other

#### 1. Transportation

1. The performance of a capacitor may be affected by the conditions during transportation.
  - 1-1. The capacitors shall be protected against excessive temperature, humidity, and mechanical force during transportation.
    - (1) Climatic condition
      - low air temperature: -40°C
      - change of temperature air/air: -25°C/+25°C
      - low air pressure: 30 kPa
      - change of air pressure: 6 kPa/min.
    - (2) Mechanical condition  
Transportation shall be done in such a way that the boxes are not deformed and forces are not directly passed on to the inner packaging.
  - 1-2. Do not apply excessive vibration, shock, or pressure to the capacitor.
    - (1) When excessive mechanical shock or pressure is applied to a capacitor, chipping or cracking may occur in the ceramic body of the capacitor.
    - (2) When the sharp edge of an air driver, a soldering iron, tweezers, a chassis, etc. impacts strongly on the surface of the capacitor, the capacitor may crack and short-circuit.
  - 1-3. Do not use a capacitor to which excessive shock was applied by dropping, etc.  
A capacitor dropped accidentally during processing may be damaged.

#### 2. Characteristics Evaluation in the Actual System

1. Evaluate the capacitor in the actual system, to confirm that there is no problem with the performance and specification values in a finished product before using.
2. Since a voltage dependency and temperature dependency exists in the capacitance of high dielectric type ceramic capacitors, the capacitance may change depending on the operating conditions in the actual system. Therefore, be sure to evaluate the various characteristics, such as the leakage current and noise absorptivity, which will affect the capacitance value of the capacitor.
3. In addition, voltages exceeding the predetermined surge may be applied to the capacitor by the inductance in the actual system. Evaluate the surge resistance in the actual system as required.

#### <Applicable to NFM Series>

4. The effects of noise suppression can vary depending on the usage conditions, including differences in the circuit or IC to be used, the type of noise, the shape of the pattern to be mounted, and the mounting location. Be sure to verify the effect on the actual device in advance.

GRM

GR3

GRJ

GR4

GR7

GJM

GQM

GA2

GA3  
GB

GA3  
GD

GA3  
GF

LLL

LLA

LLM

LLR

NFM

KRM

KR3

GMA

GMD

Notice